### 503572665 11/17/2015

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
NORIYUKI HAYASHIZAKA	08/19/2015
DAISUKE MISHOU	08/18/2015
TAKEO EBINA	09/24/2015
SATOMI HATTORI	08/20/2015
TAKAHIRO ISHIDA	08/20/2015
TOMOYUKI YAMAGUCHI	09/30/2015

#### **RECEIVING PARTY DATA**

Name:	SUMITOMO SEIKA CHEMICALS CO., LTD.
Street Address:	346-1, MIYANISHI
City:	HARIMA-CHO, KAKO-GUN, HYOGO
State/Country:	JAPAN
Postal Code:	675-0145
Name:	NATIONAL INSTITUTE OF ADVANCED INDUSTRIAL SCIENCE AND TECHNOLOGY
Street Address:	3-1, KASUMIGASEKI 1-CHOME
City:	CHIYODA-KU, TOKYO
State/Country:	JAPAN
Postal Code:	100-8921
Name:	I&P CO., LTD.
Street Address:	1050-1, TAKASAKA
City:	HIGASHIMATSUYAMA-SHI, SAITAMA
State/Country:	JAPAN
Postal Code:	355-0047

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	29533609

### **CORRESPONDENCE DATA**

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using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	Q221123 (JTC)
NAME OF SUBMITTER:	ELAINE C. BARTON
SIGNATURE:	/Elaine C. Barton/
DATE SIGNED:	11/17/2015

#### **Total Attachments: 8**

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AA T	cicas, i/wc,		
	<u>Name</u>	<u>Address</u>	
1)	Noriyuki HAYASHIZAKA	c/o SUMITOMO SEIKA CHEMICALS CO., LTD., 346-1, Miyanishi, Harima-cho, Kako-gun, Hyogo 675-0145 Japan	
2)	Daisuke MISHOU	c/o SUMITOMO SEIKA CHEMICALS CO., LTD., 346-1, Miyanishi, Harima-cho, Kako-gun, Hyogo 675-0145 Japan	
3)	Takeo EBINA	c/o Tohoku Center, National Institute of Advanced Industrial Science and Technology, Nigatake 4-2-1, Miyagino-ku, Sendai-shi, Miyagi 983-8551 Japan	
4)	Satomi HATTORI	c/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan	
5)	Takahiro ISHIDA	e/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan	
6)	Tomoyuki YAMAGUCHI	c/o L&P CO., LTD., 1050-1, Takasaka, Higashimatsuyama-shi, Saitama 355-0047 Japan	

hereinafter called assignor(s), have invented certain improvements in Molded coil

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on July 20, 2015 , Serial No. 29/533609 ; and

Whereas

Williamona There

SUMITOMO SEIKA CHEMICALS CO., LTD.

346-1, Miyanishi,

Harima-cho, Kako-gun, Hyogo 675-0145 Japan

and, National Institute of Advanced Industrial Science and Technology

3-1, Kasumigaseki 1-chome,

Chiyoda-ku, Tokyo 100-8921 Japan

and, I&P CO., LTD.

1050-1, Takasaka,

Higashimatsuyama-shi, Saitama 355-0047 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREPORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

<u>INVENTORS</u>

**DATE SIGNED** 

1):	Norigiki Dayashiyaka	August 19.2015
Name:	Noriyuki HAYASHIZAKA	<i>y</i>
2):	Daisules Mishon	August 18, 2015
Name:	Daisuke MISHOU	*
3):		
Name:	Takeo EBINA	
4):		
Name:	Satomi HATTORI	
5):		
Name:	Takahiro ISHIDA	
6):		
Name:	Tomoyuki YAMAGUCHI	

WV D	iereas, i/we,		
	<u>Name</u>	<u>Address</u>	
1)	Neriyuki HAYASHIZAKA	c/o SUMITOMO SEIKA CHEMICALS CO., LTD., 346-1, Miyanishi, Harima-cho, Kako-gun, Hyogo 675-0145 Japan	
2)	Daisuke MISHOU	c/o SUMITOMO SEIKA CHEMICALS CO., LTD., 346-1, Miyanishi, Harima-cho, Kako-gun, Hyogo 675-0145 Japan	OVERNOVATEL SCHOOL STATEMENT
3)	Takeo EBINA	c/o Tohoku Center, National Institute of Advanced Industrial Science and Technology, Nigatake 4-2-1, Miyagino-ku, Sendai-shi, Miyagi 983-8551 Japan	water the second
4)	Satomi HATTORI	c/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan	THE REPORT OF THE PERSON OF TH
5)	Takahiro ISHIDA	e/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan	GTO-NO-ES-GENERAL ELECTRICAL ELEC
6)	Tomoyuki YAMAGUCHI	o/o l&P CO., LTD., 1050-1, Takasaka, Higashimatsuyama-shi, Saitama 355-0047 Japan	

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346-1, Miyanishi,

Harima-cho, Kako-gun, Hyogo 675-0145 Japan

National Institute of Advanced Industrial Science and Technology and,

3-1, Kasumigaseki 1-chome,

Chiyoda-ku, Tokyo 100-8921 Japan

I&P CO., LTD. and,

1050-1, Takasaka,

Higashimatsuyama-shi, Saitama 355-0047 Japan

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INVENTORS

DATE SIGNED

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261) **PATENT** Page 1 of 2

1):		
Name:	Noriyuki HAYASHIZAKA	(## LO TO
2):		
Name:	Daisuke MISHOU	(2 4 1 04 Court
3):	Datieo Elem	September 24, 2015
Name:	Takeo EBINA	
4):		
Name:	Satomi HATTORI	
5):		
Name:	Takahiro ISHIDA	
6):		
Name:	Tomoyuki YAMAGUCHI	

Whereas, I/we, Name <u>Address</u> c/o SUMITOMO SEIKA CHEMICALS CO., LTD., Noriyuki HAYASHIZAKA 346-1, Miyanishi, Harima-cho, Kako-gun, Hyogo 675-0145 Japan c/o SUMITOMO SEIKA CHEMICALS CO., LTD., Daisuke MISHOU 346-1, Miyanishi, Harima-cho, 2) Kako-gun, Hyogo 675-0145 Japan c/e Tohoku Center, National Institute of Advanced Industrial Science and Technology, Takeo EBINA Nigatake 4-2-1, Miyagino-ku, Sendai-shi, Miyagi 983-8551 Japan c/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, Satomi HATTORI 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan c/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, Takahiro ISHIDA 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan e/o I&P CO., LTD.,

hereinafter called assignor(s), have invented certain improvements in Molded coil

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Higashimatsuyama-shi, Saitama 355-0047 Japan

filed on \_\_\_\_\_ July 20, 2015 , Serial No. \_\_\_\_\_ 29/533609 ; and

Whereas

and,

Tomoyuki YAMAGUCHI

SUMITOMO SEIKA CHEMICALS CO., LTD.

346-1, Miyanishi,

Harima-cho, Kako-gun, Hyogo 675-0145 Japan

1050-1, Takasaka,

National Institute of Advanced Industrial Science and Technology

3-1, Kasumigaseki 1-chome,

Chiyoda-ku, Tokyo 100-8921 Japan

and, I&P CO., LTD.

1050-1, Takasaka,

Higashimatsuyama-shi, Saitama 355-0047 Japan

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INVENTORS

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Page 1 of 2

REEL: 037058 FRAME: 0912

1):		
Name:	Noriyuki HAYASHIZAKA	
2):		
Name:	Daisuke MISHOU	
3):		_
Name:	Takeo EBINA	
4):	Satomi Hattori	Aug, 20, 2015
Name:	Satomi HATTORI	¥
5):	Takahiro Ishida	Aug. 20, 20/5
Name:	Takahiro ISHIDA	- V
6):		_
Name:	Tomoyuki YAMAGUCHI	A Mikhi a da sila da sa

Whereas, I/we, Name <u>Address</u> c/o SUMITOMO SEIKA CHEMICALS CO., LTD., Noriyuki HAYASHIZAKA 346-1, Miyanishi, Harima-cho, Kako-gun, Hyogo 675-0145 Japan c/o SUMITOMO SEIKA CHEMICALS CO., LTD., Daisuke MISHOU 21 346-1. Miyanishi, Harima-cho. Kako-gun, Hyogo 675-0145 Japan c/o Tohoku Center, National Institute of Advanced Industrial Science and Technology, Takeo EBINA 31 Nigatake 4-2-1. Miyagino-ku, Sendai-shi, Miyagi 983-8551 Japan c/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, 4) Satomi HATTORI 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan c/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, Takahiro ISHIDA 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan c/o I&P CO., LTD., Tomoyuki YAMAGUCHI 1050-1. Takasaka.

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INVENTORS

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1):		
Name:	Noriyuki HAYASHIZAKA	
2):		
Name:	Daisuke MISHOU	
3):		
Name:	Takeo EBINA	
4):		
Name:	Satomi HATTORI	
5):		
Name:	Takahiro ISHIDA	
6):	Idanagachi	Sep 30.2015
Name:	Tomoyuki YAMAGUCHI	<del></del>

**RECORDED: 11/17/2015**